Assurance Continuity Maintenance Report

BSI-DSZ-CC-1072-V4-2021-MA-01

NXP Smart Card Controller P6021y VB with IC Dedicated Software
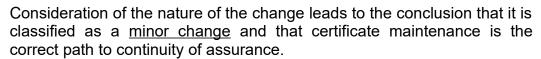
from

NXP Semiconductors Germany GmbH

SOGIS
Recognition Agreement

The IT product identified in this report was assessed according to the *Assurance Continuity: CCRA Requirements,* version 2.1, June 2012 and the developer's Impact Analysis Report (IAR). The baseline for this assessment was the Certification Report, the Security Target and the Evaluation Technical Report of the product certified by the Federal Office for Information Security (BSI) under BSI-DSZ-CC-1072-V4-2021.

The certified product itself did not change. The changes are related to an update of life cycle security aspects covered by updated audits and newest site certificates. Also three sites were added.

Consideration of the nature of the change leads to the conclusion that it is classified as a <u>minor change</u> and that certificate maintenance is the correct path to continuity of assurance.

The resistance to attacks has <u>not</u> been re-assessed in the course of this maintenance process. Therefore, the assurance statement as outlined in the Certification Report BSI-DSZ-CC-1072-V4-2021 dated 24 June 2021 is of relevance and has to be considered when using the product. Details can be found on the following pages.

This report is an addendum to the Certification Report BSI-DSZ-CC-1072-V4-2021.

Common Criteria

Common Criteria
Recognition Arrangement
recognition for components
up to EAL 2

Bonn, 17 December 2021

The Federal Office for Information Security

DAkkS
Deutsche
Akkreditierungsstelle
D-ZE-19615-01-00

Assessment

The IT product identified in this report was assessed according to the *Assurance Continuity: CCRA Requirements* [1] and the Impact Analysis Report (IAR) [2]. The baseline for this assessment was the Certification Report of the certified product (Target of Evaluation, TOE) [3], its Security Target and the Evaluation Technical Report as outlined in [3].

The vendor for the NXP Smart Card Controller P6021y VB with IC Dedicated Software, NXP Semiconductors Germany GmbH, submitted an IAR [2] to the BSI for approval. The IAR is intended to satisfy the requirements outlined in the document *Assurance Continuity: CCRA Requirements* [1]. In accordance with those requirements, the IAR describes (i) the changes made to the certified TOE, (ii) the evidence updated as a result of the changes and (iii) the security impact of the changes.

The certified product itself did not change.

The changes are related to an update of life cycle security aspects. Also three sites were added. The ALC re-evaluation was performed by the ITSEF TUV Informationstechnik GmbH. The procedure led to an updated version of the Evaluation Technical Report (ETR) [5]. The ETR for Composition [6] was not renewed. The Common Criteria assurance requirements for ALC are fulfilled as claimed in the Security Target [4].

The Common Criteria assurance requirements ALC-Life cycle support (i.e. ALC_CMC.5, ALC_CMS.5, ALC_DEL.1, ALC_DVS.2, ALC_FLR.1, ALC_LCD.1 and ALC_TAT.3) are fulfilled for the development and production sites of the TOE listed below.

Name of the Site	Company Name /Adress	Function	Reference / Date
Development			
NXP Hamburg	NXP Semiconductors Germany GmbH Troplowitzstr. 20, 22529 Hamburg, Germany	Development and IT support Wafer testing and wafer treatment Flaw Remediation Delivery	BSI-DSZ-CC-S-0124-2019-MA-02 Audit date: 2019-06-24
NXP Eindhoven	NXP Semiconductors Germany GmbH NXP Semiconductors Eindhoven HTC-46.3 West Building 46, High Tech Campus 5656AE, Eindhoven, Netherlands	Development	BSI-DSZ-CC-S-0193-2021 Audit date: 2021-05-04
Sii Gdansk	SII SP.ZO.O Olivia Prime 10th floor Grunwaldzka 472E, 80-309 Gdansk, Poland	SW development	ANSSI-CC-SITE-2021/11 Audit date: 2021-08-12
NXP Nijmegen	NXP Semiconductors Nijmegen B.V. Gerstweg 2, 6534AE Nijmegen, Netherlands	Development support (sample preparation, design data verification) Failure analysis lab	BSI-DSZ-CC-S-0190-2021 Audit date: 2021-06-15
NXP Gratkorn	NXP Semiconductors Austria GmbH Mikron-Weg 1, 8108 Gratkorn, Austria	Document control	BSI-DSZ-CC-S-0186-2021 Audit date: 2021-05-04
NXP IT Eindhoven Secure Room	NXP Semiconductors Netherlands B.V., Building 60, High Tech Campus Secure Room 131 5656AE, Eindhoven, Netherlands	IT support (admin room)	NSCIB-SS-38181-CR4 Audit date: 2020-05-27
NXP Bangalore	NXP India Private Limited Manyata Tech Park Nagawara Village, Kasaba Hobli, Bangalore 560045, India	SW development	BSI-DSZ-CC-S-0179-2021 Audit date: 2021-09-30

Digital Reality Phoenix	Digital Realty Data Center 120 East Van Buren St, Phoenix, AZ 85004 United States of America	IT support (TOE database)	ANSSI-CC-SITE-2021/08 Audit date: 2021-02-23
Colt Hamburg	Colt Hamburg Obenhauptstrasse 1C, 22335 Hamburg, Germany	IT support (TOE database)	ANSSI-CC-SITE-2021/12 Audit date: 2021-07-01
Akquinet Hamburg	Akquinet Hamburg Ulzburger Strasse 201, 22850 Norderstedt, Germany	IT support (TOE database)	ANSSI-CC-SITE-2021/01 Audit date: 2020-08-21
Equinix Singapore	EQUINIX 20 Ayer Rajah Crescent, IBX SG1, Level 5 Unit 5, Ayer Rajah Industrial Park 139964 Singapore	Data center	ANSSI-CC-SITE-2021/07 Audit date: 2021-02-23
NXP Bucharest	NXP Semiconductors Romania Campus 6, Bulevardul Iuliu Maniu 6L, 061103 Bucuresti Romania	IT engineering and support	ANSSI-CC-SITE-2020/10 Audit date: 2019-12-18
NXP Guadalajara	NXP Guadalajara Periferico Sur #8110 Col. El Mante JALISCO, 45609 Tlaquepaque Mexico	IT engineering and support	ANSSI-CC-SITE-2020/11 Audit date: 2019-12-11
Production			
TSMC Tainan and Hsinchu	Taiwan Semiconductor Manufacturing Company Limited Fab 14A: 1-1, Nan-Ke North Rd., Tainan Science Park, Tainan 741-44, Taiwan, R.O.C., Fab 2 and 5: 121, Park Ave. 3, Hsinchu Science Park, Hsinchu 300-77, Taiwan, R.O.C., Fab 8: 25, Li-Hsin Rd., Hsinchu Science Park, Hsinchu, 300-78 Taiwan, R.O.C.	Mask production and diffusion	BSI-DSZ-CC-S-0157-2020 Audit date: 2020-04-06

Chipbond Hsinchu City	Chipbond Technology Corporation No. 3, Li-Hsin Rd. V Science Based Industrial Park Hsin-Chu City Taiwan, R.O.C.	Bumping	Virtual audit: 2021-09-15
NXP Hamburg (formerly TCE-H)	See NXP Hamburg	See NXP Hamburg	See NXP Hamburg
See NXP Hamburg	NXP Semiconductors Thailand (ATBK) 303 Moo 3 Chaengwattana Rd. Laksi Bangkok 10210 Thailand	Wafer testing, wafer treatment, assembly, and Final Test Test program development Failure analysis lab Delivery	BSI-DSZ-CC-S-0206-2021 Audit date: 2021-09-29
NXP ATKH	NXP Semiconductors Taiwan Ltd (ATKH) 10, Chin 5th Road, N.E.P.Z Kaohsiung 81170 Taiwan R.O.C	Wafer testing, wafer treatment, assembly, and Final Test Test program development Failure analysis lab Delivery	BSI-DSZ-CC-S-0148-2019 Audit date: 2019-09-09
Linxens Ayutthaya	AY1, Linxens (Thailand) Co Ltd. 142 Moo, Hi-Tech Industrial Estate Tambon Ban Laean, Amphor Bang-Pa-In 13160 Ayutthaya Thailand	Inlay assembly	BSI-DSZ-CC-S-0143-2019 Audit date: 2019-10-22
HID Global Malaysia	HID Global Sdn. Bhd. No. 2, Jalan i-Park 1/1 Kawasan Perindustrian i-Park Bandar Indahpura 81000 Kulai, Johor Malaysia	Inlay assembly	BSI-DSZ-CC-S-0189-2021 Audit date: 2021-09-06

Production Sites (not part of f life-cycle of the TOE)			
The following sites were audited within the course of this evaluation, however these sites are not part of the life-cycle of the TOE. The audit results are documented in the corresponding site visit check lists and STARs.			
PDMC Hsinchu	Photronics DNP Mask Corp, Hsinchu, Hsinchu 1A (Head Office), 1F, No.2, Li-Hsin Rd., Science Based Industrial Park, Hsin-Chu City, 30078, Taiwan R.O.C.; Hsinchu 1D, No.6, Li-Hsin 7th Rd., Science Based Industrial Park, Hsin-Chu City, 30078, Taiwan R.O.C.	Wafer bumping	Virtual Audit: 2021-09-14
PSGP Singapore	Photronics, No 33 Ubi Avenue 3, # 03 – 09, Vertex Building, Singapore 408868	Mask production	Document Based evaluation: 2021-06-10
SSMC Singapore	Systems on Silicon Manufacturing Co. Pte. Ltd., 70 Pasir Ris Industrial Drive 1, Singapore 519527	Wafer Production	Virtual Audit: 2021-06-10

Table 1: Relevant development/production sites for the TOE

The partial ALC re-evaluation resulted in an updated STAR for ALC-Reuse for the following sites:

- Chipbond Technology Corporation, Hsinchu [7]
- Photronics DNP Mask Corp, Hsinchu [8]
- Photronics, Singapore [9]
- Systems on Silicon Manufacturing Co. Pte. Ltd., Singapore [10]

Conclusion

The maintained change is at the level of life cycle security aspects. The ITSEF has audited sites and evaluated the described changes or integrated existing site certificates to provide an updated ETR [5] which has been approved by the Certification Body of BSI. The ETR for Composition was not updated and remains as included in the Certification Report BSI-DSZ-CC-1072-V4-2021 [6].

The resistance to attacks has <u>not</u> been re-assessed in the course of this maintenance process. Therefore, the assurance statement as outlined in the Certification Report BSI-DSZ-CC-1072-V4-2021 dated dated 24 June 2021 is of relevance and has to be considered when using the product.

Obligations and notes for the usage of the product:

All aspects of assumptions, threats and policies as outlined in the Security Target not covered by the TOE itself need to be fulfilled by the operational environment of the TOE.

The customer or user of the product shall consider the results of the certification within his system risk management process. In order for the evolution of attack methods and techniques to be covered, he should define the period of time until a re-assessment for the TOE is required and thus requested from the sponsor of the certificate.

This report is an addendum to the Certification Report [3].

References

[1]   Common Criteria document "Assurance Continuity: CCRA Requirements", version 2.1, June 2012

[2]   NXP Secure Smart Card Controller P6021yVB Impact Analysis Report, Version 0.1, 2020-11-04, NXP Semiconductors (confidential document)

[3]   Certification Report BSI-DSZ-CC-1072-V4-2021 for NXP Secure Smart Card Controller P6021y VB* including IC Dedicated Software, Bundesamt für Sicherheit in der Informationstechnik

[4]   Security Target BSI-DSZ-CC-1072-V4-2021, NXP Secure Smart Card Controller P6021y VB – Security Target, Version 1.11, 2019-08-23, NXP Semiconductors (confidential document)

[5]   Evaluation Technical Report BSI-DSZ-CC-1072-V4-MA-01, Version 2, 2021-12-09, TÜV Informationstechnik GmbH ´(confidential document)

[6]   Evaluation Technical for Composite Evaluation (ETR COMP) for the P6021y VB, version 3, 2021-06-16, TÜV Informationstechnik GmbH (confidential document)

[7]   Site Technical Audit Report (STAR) Chipbond Technology Corporation, Hsinchu, Version 1, 2021-10-26, TÜV Informationstechnik GmbH

[8]   Site Technical Audit Report (STAR) Photronics DNP Mask Corp, Hsinchu, Version 1, 2021-10-26, TÜV Informationstechnik GmbH

[9]   Site Technical Audit Report (STAR) Photronics, Singapore, Version 1, 2021-10-26, TÜV Informationstechnik GmbH

[10]   Site Technical Audit Report (STAR) Systems on Silicon Manufacturing Co. Pte. Ltd., Singapore, Version 1, 2021-10-26, TÜV Informationstechnik GmbH